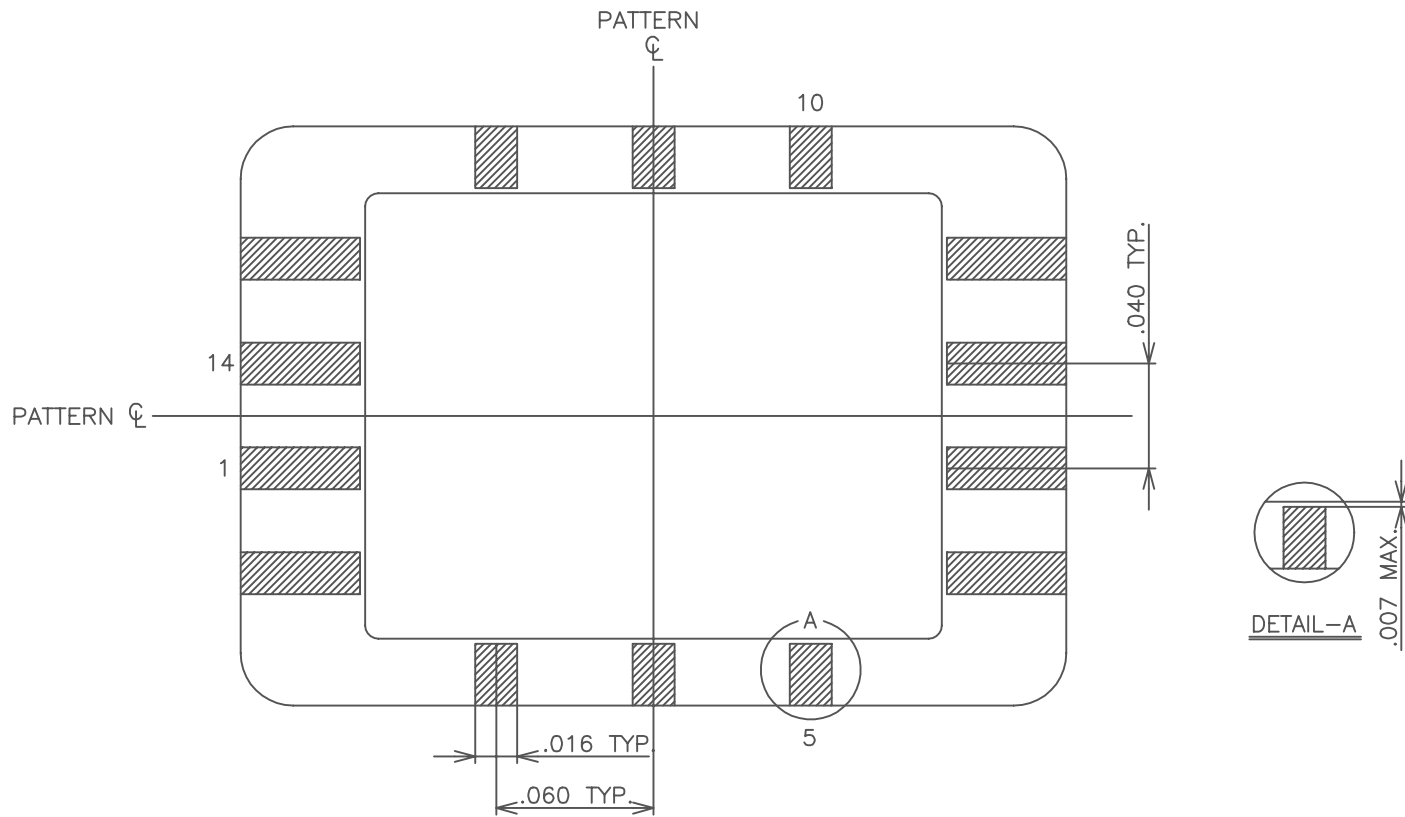


NOTES:

1. PLATING THICKNESS TO BE PER CUSTOMER'S SPECIFICATION.
2. LEAD RESISTANCE : 0.2 Ω MAX.
3. SEAL AREA TO BE METALLIZED.
4. DIE ATTACH AREA TO BE METALLIZED.
5. SEAL RING AND DIE ATTACH PAD TO BE FLOATING FROM ANY PINS.

SB014M528-1				S=0 D=0
DRAWN	CHECKED	APPROVED	DATE	
T.H	K.M		JUL.29.'82	
DRAWING NO.				SHEET
KD-82528-B				1/2

MODIFICATION						NAME	TOLERANCE	
						14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	
	△	CONVERTED CAD DATA , ADDED SHEET 2/2	JAN.31.'00	T.K M.SU	H.TA S.K	H.SA	SCALE	MATERIAL
	△	CHANGED : .225 → .221	AUG.9.'82	T.H	K.M		5 / 1	AS INDICATED
	CHANGED	DATE	DRAWN	CHECKED	APPROVED		±.005 THIRD ANGLE PROJECTION	
								KYOCERA CORPORATION KYOTO JAPAN



BONDING PATTERN

MODIFICATION						NAME	TOLERANCE	DRAWN	CHECKED	APPROVED	DATE
						14 LEAD SIDE BRAZED PACKAGE	UNLESS OTHERWISE SPECIFIED	T.H	K.M		JUL.29.'82
						SCALE 20 / 1	MATERIAL				
							THIRD ANGLE PROJECTION				
	CHANGED	DATE	DRAWN	CHECKED	APPROVED	 KYOCERA CORPORATION KYOTO JAPAN	DRAWING NO.	KD-82528-B		SHEET 2 / 2	